

## G593-SD1-LAX3

HPC Server - 5U DP NVIDIA HGX™ H200 8-GPU



### Features

- CPU+GPU Direct liquid cooling solution
- Liquid cooled NVIDIA HGX™ H200 8-GPU
- 900GB/s GPU-to-GPU bandwidth with NVLink® and NVSwitch™
- Dual 5th/4th Gen Intel® Xeon® Scalable Processors
- Dual Intel® Xeon® CPU Max Series
- 8-Channel DDR5 RDIMM, 32 x DIMMs
- Dual ROM Architecture
- Compatible with NVIDIA BlueField®-3 DPUs/SuperNICs
- 2 x 10Gb/s LAN ports via Intel® X710-AT2
- 8 x 2.5" Gen5 NVMe/SATA/SAS-4 hot-swappable bays
- 4 x FHHL PCIe Gen5 x16 slots
- 8 x LP PCIe Gen5 x16 slots
- 4+2 3000W 80 PLUS Titanium redundant power supplies

### Specification

<b>Dimensions</b>	5U (W447 x 219.7 x 945 mm)	<b>Application</b>	AI, AI Inference, AI Training, High-Performance Computing...
<b>Motherboard</b>	MSB3-G41	<b>TPM</b>	1 x TPM header with SPI interface Optional TPM2.0 kit: CTM010
<b>GPU</b>	Liquid cooled NVIDIA HGX™ H200 8-GPU (8-root ports)	<b>Backplane Board</b>	Speed and bandwidth: PCIe Gen5 x4 or SATA 6Gb/s or SAS-4 24Gb/s
<b>CPU</b>	5th/4th Generation Intel® Xeon® Scalable Processors Intel® Xeon® CPU Max Series Dual processor, TDP up to 350W	<b>Power Supply</b>	4+2 3000W 80 PLUS Titanium redundant power supply AC Input: 115-240V *The system power supply requires C19 power cord.
<b>Socket</b>	2 x LGA 4677 (Socket E)	<b>System Management</b>	ASPEED® AST2600 Baseboard Management Controller GIGABYTE Management Console web interface
<b>Chipset</b>	Intel® C741 Chipset	<b>OS Compatibility</b>	Windows Server, Red Hat Enterprise Linux Server, VMware ESXi, SUSE Linux Enterprise, Ubuntu Server, Citrix Hypervisor
<b>Memory</b>	8-Channel DDR5 memory, 32 x DIMM slots RDIMM up to 96GB; 3DS RDIMM up to 256GB supported Memory speed: Up to 5600 MT/s (1DPC), 4400 MT/s (2DPC)	<b>System Fans</b>	6 x 40x40x28mm (25,000rpm), 2 x 40x40x56mm (32,000rpm), 3 x 60x60x56mm (24,000rpm), 4 x 80x80x80mm (17,000rpm)
<b>LAN</b>	2 x 10Gb/s LAN ports (1 x Intel® X710-AT2) - Support NCSI function 1 x 10/100/1000 management LAN	<b>Operating Properties</b>	Operating temperature: 10°C to 35°C Operating humidity: 8-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
<b>Video</b>	Integrated in ASPEED® AST2600 - 1 x VGA port	<b>Packaging Content</b>	1 x G593-SD1-LAX3, 1 x CoolIT CPU cold plate loop, 6 x Carrier clips, 1 x L-shape Rail kit Packaging Dimensions: 1200 x 890 x 700 mm
<b>Storage</b>	8 x 2.5" Gen5 NVMe/SATA/SAS4 hot-swappable HDD/SSD bays *SAS card is required to support SAS drives.	<b>Part Numbers</b>	Barebone w/ NVIDIA module: 6NG593SD1DR000LBX3* Optional parts: - C19 power cord 125V/15A (US): 25CP1-018000-Q0R - C19 power cord 250V/16A (EU): 25CP3-01830H-Q0R - C19 power cord 125V/15A (JP): 25CPA-01830B-Q0R
<b>RAID</b>	Intel® SATA RAID 0/1/10/5 Support optional RAID add-in cards		
<b>Expansion Slots</b>	4 x PCIe x16 (Gen5 x16) FHHL slots 8 x PCIe x16 (Gen5 x16) low-profile slots		
<b>I/O Ports</b>	Front: 2 x USB 3.2 Gen1, 1 x VGA, 2 x RJ45, 1 x MLAN (default) Rear: 1 x MLAN Internal: 1 x TPM header, 1 x VROC connector		



Learn more at <https://www.GIGABYTE.com/enterprise>

\* All specifications are subject to change without notice. Please visit our website for the latest information.  
\* Intel, the Intel logo, Xeon, and other Intel marks are trademarks of Intel Corporation or its subsidiaries.  
\* NVIDIA, the NVIDIA logo are trademarks and/or registered trademarks of NVIDIA Corporation in the U.S. and other countries. All other brands, logos and names are property of their respective owners.

© 2024 Giga Computing Technology Co., Ltd. All rights reserved.

Designed by

